Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
	70	(US-20030080437-\$).did. or (US-4811081-\$ or US-5034245-\$ or US-5502889-\$ or US-5518964-\$ or US-5604379-\$ or US-5657104-\$ or US-5657206-\$ or US-5677576-\$ or US-5749997-\$ or US-5813870-\$ or US-5819406-\$ or US-5846853-\$ or US-5819406-\$ or US-5886415-\$ or US-5918113-\$ or US-5945729-\$ or US-6008072-\$ or US-6011315-\$ or US-6028365-\$ or US-6031590-\$ or US-6103553-\$ or US-6121688-\$).did. or (US-6133637-\$ or US-6137183-\$ or US-6140707-\$ or US-6147311-\$ or US-6175151-\$ or US-628687-\$ or US-6204564-\$ or US-628687-\$ or US-6337254-\$ or US-633552-\$ or US-6307254-\$ or US-6335504-\$ or US-6410366-\$ or US-6410364-\$ or US-647029-\$ or US-6410364-\$ or US-6458236-\$).did. or (US-6458609-\$ or US-6461890-\$ or US-6458236-\$).did. or (US-6458609-\$ or US-6551918-\$ or US-6521483-\$ or US-6551918-\$ or US-6520627-\$ or US-6551918-\$ or US-6620652-\$ or US-6784555-\$ or US-6919627-\$ or US-RE38053-\$).did.	US-PGPUB; USPAT	OR	ON	2005/12/16:09:00
L2	0	("6919627").URPN.	USPAT	OR	ON	2005/12/16 09:06
L3	5	("20030054162" "20030141582" "5323060" "6005778" "6388313").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:10
L4	1	09/954262	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L5	6	("5034245").URPN.	USPAT	OR	ON	2005/12/16 09:22

L6	13	("3391455" "3951063" "4049844" "4075049" "4327124" "4401686" "4469777" "4572764" "4654752" "4807021" "4814090" "4863757").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:23
L7	5	"6352775"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L8	28	"6410415"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L9	3	"6403711"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L10	4	"5326845"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L11	61	"4491553"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:25
L12	101	7 8 9 10 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:26
L13	101	12 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:26

L14	84	12 and (filler particle microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:32
L15	687442	(chip die semiconductor) with (substrate carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L16	11188	adhesive near4 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L17	1482	15 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L18	8877	adhesive near3 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:33
L19	474624	(chip die semiconductor) near3 (substrate carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:34
L20	936	19 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:34
L21	9388	(partical filler microparticle) near3 diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35

L22	105	20 and 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35
L23	103	22 not 1 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 09:35
L24	0	("6635956").URPN.	USPAT	OR	ON	2005/12/16 09:47
L25	2	("6001671" "6459549").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/16 09:47

L2	8877	adhesive near3 (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L3	242	2 with diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
L4	83	3 and (chip die ((semiconductor electronic optical) near1 (element device)) with (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:19
L5	189	4not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:05
L6	80	4 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:05
L7	83	3 and (chip die ((semiconductor electronic optical) near1 (element device)) same (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:20
L8	87	3 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
<u>1</u> 9	4	8 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:20

L10	3185	2 and diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:21
L11	1215	10 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:22
L12	594	2 same diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L13	177	12 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L14	90	13 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:22
L15	26389	adhesive with (partical filler microparticle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L16	1556	15 same diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:29
L17	422	16 and (chip die ((semiconductor electronic optical) near1 (element device)) and (substrate board pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/16 16:30

L18	245	17 not 13	US-PGPUB; USPAT; USOCR;	OR	ON	2005/12/16 16:30
			EPO; JPO;			
			DERWENT; IBM_TDB			